## **CNA1312K**

## Photo Interrupter

For contactless SW and object detection

#### Overview

CNA1312K is an ultraminiature, highly reliable transmissive photosensor in which a high efficiency GaAs infrared light emitting diode chip and a high sensitivity Si phototransistor chip are integrated in a double molded resin package.

#### ■ Features

- Ultraminiature: 2.6 mm × 4.9 mm (height: 3.3 mm)
- Highly precise position detection: 0.1 mm
- Gap width: 2.0 mm

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

F	Symbol	Rating	Unit	
Input (Light emitting diode)	Power dissipation *1	$P_{\mathrm{D}}$	75	mW
	Forward current	$I_{\mathrm{F}}$	50	mA
	Reverse voltage	$V_R$	6	V
Output (Photo transistor)	Collector-emitter voltage (Base open)	V <sub>CEO</sub> 35		V
	Emitter-collector voltage (Base open)	V <sub>ECO</sub>	6	V
	Collector current	$I_{C}$	20	mA
	Collector power dissipation *2	$P_{C}$	75	mW
Operating ambient temp	T <sub>opr</sub>	-25 to +85	°C	
Storage temperature		T <sub>stg</sub>	-40 to +100	°C

Note) \*1: Input power derating ratio is 1.0 mW/°C at  $T_a \ge 25$ °C

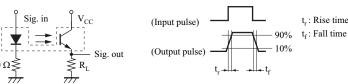
#### ■ Electrical-Optical Characteristics $T_a = 25$ °C±3°C

Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Input characteristics	Reverse current	$I_R$	$V_R = 3 V$			10	μА
	Forward voltage	V <sub>F</sub>	$I_F = 20 \text{ mA}$		1.2	1.4	V
Output characteristics	Collector-emitter cutoff current (Base open)	$I_{CEO}$	$V_{CE} = 20 \text{ V}$			100	nA
Transfer characteristics	Collector current	$I_{C}$	$V_{CE} = 5 \text{ V}, I_F = 5 \text{ mA}$	40		400	μΑ
	Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_F = 10 \text{ mA}, I_C = 50 \mu\text{A}$			0.4	V
	Rise time *	t <sub>r</sub>	$V_{CC} = 5 \text{ V}, I_C = 0.1 \text{ mA},$		50		μs
	Fall time *	$t_{\mathrm{f}}$	$R_{\rm L} = 1000\Omega$		50		μs

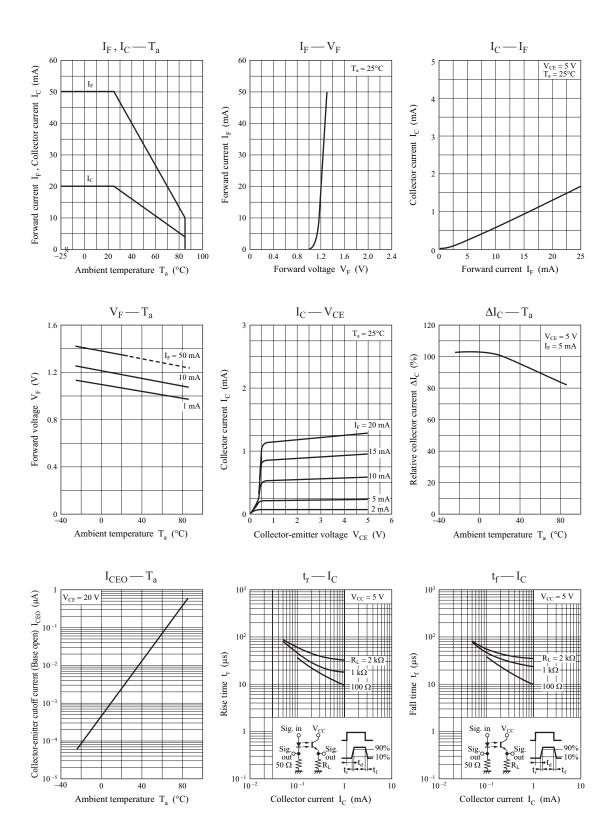
Note) 1. Input and output are practiced by electricity.

2. This device is designed by disregarding radiation.

3. \*: Switching time measurement circuit

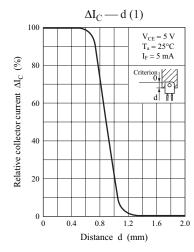


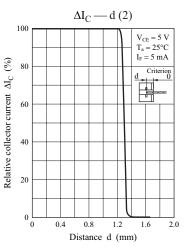
<sup>\*2:</sup> Output power derating ratio is 1.0 mW/°C at  $T_a \ge 25$ °C



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Panasonic CNA1312K

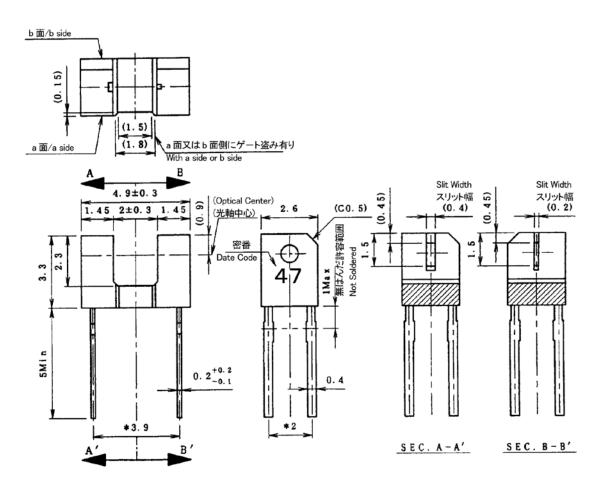


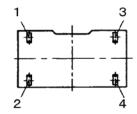


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#### ■ Package (Unit: mm)

## LSMSIN4S0003





- (注 1) \*リード根元寸法とします。/(Note1) \* Indicates root dimensions of lead.
- (注 2) 指示無き寸法公差は±0.2。/(Note2)Not appointment tolerance :±0.2.
- (注3) 密番は、目視又は顕微鏡に於いて解読できる事。

(Note3)What a date code sees an attention and can decode in a microscope.

- Pin name
  - 1: Anode
  - 2: Cathode
  - 3: Collector
  - 4: Emitter

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